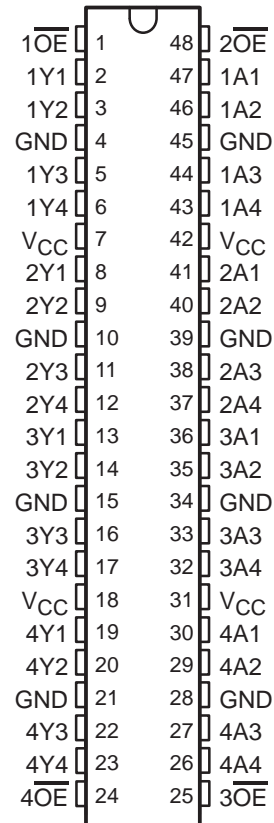


SN54ALVTH16244, SN74ALVTH16244 2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCES070G – JUNE 1996 – REVISED MAY 1999

- Members of the Texas Instruments *Widebus™* Family
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation
- 5-V I/O Compatible
- High Drive Capability (–32 mA/64 mA)
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.3 V
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Auto3-State Eliminates Bus Current Loading When Voltage at the Output Exceeds V_{CC}
- I_{off} and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model ($C = 200$ pF, $R = 0$)
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV) Packages, and 380-mil Fine-Pitch Ceramic Flat (WD) Package

SN54ALVTH16244 . . . WD PACKAGE
SN74ALVTH16244 . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



NOTE: For tape and reel order entry:
The DGGR package is abbreviated to GR, and
the DGVR package is abbreviated to VR.

description

The 'ALVTH16244 devices are 16-bit buffers/line drivers designed for 2.5-V or 3.3-V V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment. These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments Incorporated.

UNLESS OTHERWISE NOTED this document contains PRODUCTION DATA information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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SN54ALVTH16244, SN74ALVTH16244

2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

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description (continued)

When V_{CC} is between 0 and 1.2 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.2 V, the output-enable (\overline{OE}) input should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

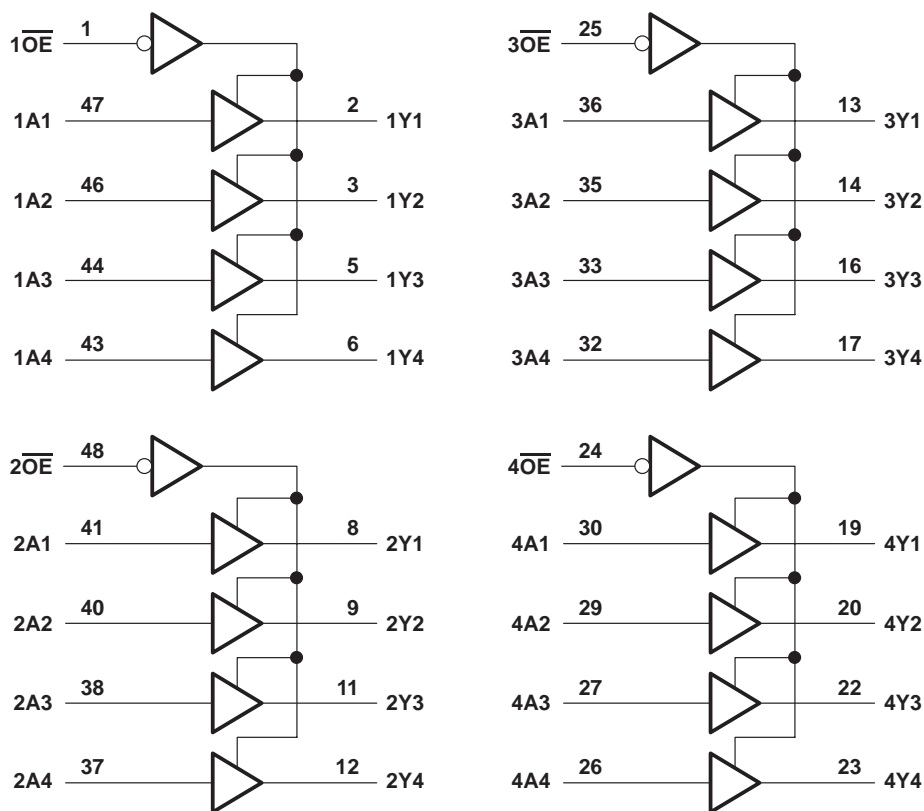
These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

The SN54ALVTH16244 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ALVTH16244 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE
(each buffer)

INPUTS		OUTPUT
\overline{OE}	A	Y
L	H	H
L	L	L
H	X	Z

logic diagram (positive logic)



SN54ALVTH16244, SN74ALVTH16244 2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, V_O (see Note 1)	–0.5 V to V_{CC} to 7V
Output current in the low state, I_O : SN54ALVTH16244	96 mA
SN74ALVTH16244	128 mA
Output current in the high state, I_O : SN54ALVTH16244	–48 mA
SN74ALVTH16244	–64 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	89°C/W
DGV package	93°C/W
DL package	94°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions, $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$ (see Note 3)

		SN54ALVTH16244		SN74ALVTH16244		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	2.3	2.7	2.3	2.7	V
V_{IH}	High-level input voltage	1.7		1.7		V
V_{IL}	Low-level input voltage		0.7		0.7	V
V_I	Input voltage	0	5.5	0	5.5	V
I_{OH}	High-level output current		–6		–8	mA
I_{OL}	Low-level output current		6		8	mA
	Low-level output current; current duty cycle $\leq 50\%$; $f \geq 1\text{ kHz}$		18		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		10		10	ns/V
	Outputs enabled					
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		200		$\mu\text{s/V}$
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54ALVTH16244, SN74ALVTH16244
2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

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recommended operating conditions, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (see Note 3)

		SN54ALVTH16244		SN74ALVTH16244		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	3	3.6	3	3.6	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	5.5	0	5.5	V
I_{OH}	High-level output current		-24		-32	mA
I_{OL}	Low-level output current		24		32	mA
	Low-level output current; current duty cycle $\leq 50\%$; $f \geq 1\text{ kHz}$		48		64	
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10	10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		200		$\mu\text{s/V}$
T_A	Operating free-air temperature	-55	125	-40	85	$^{\circ}\text{C}$

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54ALVTH16244, SN74ALVTH16244
2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range,
 $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	SN54ALVTH16244		SN74ALVTH16244		UNIT
			MIN	TYP†	MAX	MIN	
V_{IK}		$V_{CC} = 2.3\text{ V}$, $I_I = -18\text{ mA}$			-1.2		V
V_{OH}		$V_{CC} = 2.3\text{ V to } 2.7\text{ V}$, $I_{OH} = -100\text{ }\mu\text{A}$	$V_{CC}-0.2$		$V_{CC}-0.2$		V
		$V_{CC} = 2.3\text{ V}$	1.8		1.8		
V_{OL}		$V_{CC} = 2.3\text{ V to } 2.7\text{ V}$, $I_{OL} = 100\text{ }\mu\text{A}$	0.2		0.2		V
		$V_{CC} = 2.3\text{ V}$	0.4		0.4		
			0.5		0.5		
			0.5		0.5		
I_I	Control inputs	$V_{CC} = 2.7\text{ V}$, $V_I = V_{CC}\text{ or GND}$	± 1		± 1		μA
		$V_{CC} = 0\text{ or } 2.7\text{ V}$, $V_I = 5.5\text{ V}$	10		10		
	Data inputs	$V_{CC} = 2.7\text{ V}$	1		1		
			-5		-5		
I_{off}		$V_{CC} = 0$, $V_I\text{ or } V_O = 0\text{ to } 4.5\text{ V}$			± 100		μA
$I_{I(\text{hold})}$	Data inputs	$V_{CC} = 2.3\text{ V}$	115		115		μA
			-10		-10		
		$V_{CC} = 2.7\text{ V}^\ddagger$, $V_I = 0\text{ to } 2.7\text{ V}$	± 300		± 300		
I_{EX}^\S		$V_{CC} = 2.3\text{ V}$, $V_O = 5.5\text{ V}$	125		125		μA
$I_{OZ(\text{PU/PD})}^\parallel$		$V_{CC} \leq 1.2\text{ V}$, $V_O = 0.5\text{ V to } V_{CC}$, $V_I = \text{GND or } V_{CC}$, $\overline{OE} = \text{don't care}$	± 100		± 100		μA
I_{OZH}		$V_{CC} = 2.7\text{ V}$	5		5		μA
I_{OZL}		$V_{CC} = 2.7\text{ V}$	-5		-5		μA
I_{CC}		$V_{CC} = 2.7\text{ V}$, $I_O = 0$, $V_I = V_{CC}\text{ or GND}$	0.04 0.1		0.04 0.1		mA
			2.3 4.5		2.3 4.5		
			0.04 0.1		0.04 0.1		
C_i		$V_{CC} = 2.5\text{ V}$, $V_I = 2.5\text{ V or } 0$	3		3		pF
C_o		$V_{CC} = 2.5\text{ V}$, $V_O = 2.5\text{ V or } 0$	6		6		pF

† All typical values are at $V_{CC} = 2.5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

§ Current into an output in the high state when $V_O > V_{CC}$

¶ High-impedance state during power up/power down

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2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range,
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54ALVTH16244		SN74ALVTH16244		UNIT	
			MIN	TYP†	MAX	MIN		TYP†
V_{IK}	$V_{CC} = 3\text{ V}$, $I_I = -18\text{ mA}$		-1.2		-1.2		V	
V_{OH}	$V_{CC} = 3\text{ V to } 3.6\text{ V}$, $I_{OH} = -100\text{ }\mu\text{A}$		$V_{CC}-0.2$		$V_{CC}-0.2$		V	
	$V_{CC} = 3\text{ V}$	$I_{OH} = -24\text{ mA}$	2		2			
V_{OL}	$V_{CC} = 3\text{ V to } 3.6\text{ V}$, $I_{OL} = 100\text{ }\mu\text{A}$		0.2		0.2		V	
	$V_{CC} = 3\text{ V}$	$I_{OL} = 16\text{ mA}$			0.4			
		$I_{OL} = 24\text{ mA}$	0.5					
		$I_{OL} = 32\text{ mA}$			0.5			
		$I_{OL} = 48\text{ mA}$	0.55					
		$I_{OL} = 64\text{ mA}$			0.55			
I_I	Control inputs	$V_{CC} = 3.6\text{ V}$, $V_I = V_{CC}$ or GND	± 1		± 1		μA	
		$V_{CC} = 0$ or 3.6 V , $V_I = 5.5\text{ V}$	10		10			
	Data inputs	$V_{CC} = 3.6\text{ V}$	$V_I = 5.5\text{ V}$	20		20		
			$V_I = V_{CC}$	1		1		
		$V_I = 0$	-5		-5			
I_{off}	$V_{CC} = 0$, V_I or $V_O = 0$ to 4.5 V				± 100		μA	
$I_I(\text{hold})$	Data inputs	$V_{CC} = 3\text{ V}$	$V_I = 0.8\text{ V}$	75		75		μA
			$V_I = 2\text{ V}$	-75		-75		
		$V_{CC} = 3.6\text{ V}^\ddagger$, $V_I = 0$ to 3.6 V	± 500		± 500			
I_{EX}^\S	$V_{CC} = 3\text{ V}$, $V_O = 5.5\text{ V}$		125		125		μA	
$I_{OZ}(\text{PU/PD})^\parallel$	$V_{CC} \leq 1.2\text{ V}$, $V_O = 0.5\text{ V to } V_{CC}$, $V_I = \text{GND or } V_{CC}$, $\overline{OE} = \text{don't care}$		± 100		± 100		μA	
I_{OZH}	$V_{CC} = 3.6\text{ V}$	$V_O = 3\text{ V}$, $V_I = 0.8\text{ V or } 2\text{ V}$	5		5		μA	
I_{OZL}	$V_{CC} = 3.6\text{ V}$	$V_O = 0.5\text{ V}$, $V_I = 0.8\text{ V or } 2\text{ V}$	-5		-5		μA	
I_{CC}	$V_{CC} = 3.6\text{ V}$, $I_O = 0$, $V_I = V_{CC}$ or GND	Outputs high	0.07	0.1	0.07	0.1	mA	
		Outputs low	3.2	5	3.2	5		
		Outputs disabled	0.07	0.1	0.07	0.1		
$\Delta I_{CC}^\#$	$V_{CC} = 3\text{ V to } 3.6\text{ V}$, One input at $V_{CC} - 0.6\text{ V}$, Other inputs at V_{CC} or GND		0.4		0.4		mA	
C_i	$V_{CC} = 3.3\text{ V}$, $V_I = 3.3\text{ V or } 0$		3		3		pF	
C_o	$V_{CC} = 3.3\text{ V}$, $V_O = 3.3\text{ V or } 0$		6		6		pF	

† All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

§ Current into an output in the high state when $V_O > V_{CC}$

¶ High-impedance state during power up/power down

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



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2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range, $C_L = 30 \text{ pF}$, $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ALVTH16244		SN74ALVTH16244		UNIT
			MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	3.1	1	3	ns
t_{PHL}			1	3.6	1	3.5	
t_{PZH}	\overline{OE}	Y	1.1	6	1.1	5.9	ns
t_{PZL}			1.1	4.8	1.1	4.7	
t_{PHZ}	\overline{OE}	Y	1.5	4.5	1.5	4.4	ns
t_{PLZ}			1	3.5	1	3.4	

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$, $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ALVTH16244		SN74ALVTH16244		UNIT
			MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	2.6	1	2.4	ns
t_{PHL}			1	2.6	1	2.5	
t_{PZH}	\overline{OE}	Y	1	3.9	1	3.8	ns
t_{PZL}			1	3	1	2.9	
t_{PHZ}	\overline{OE}	Y	1.5	4.3	1.5	4.2	ns
t_{PLZ}			1.5	3.7	1.5	3.6	

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.

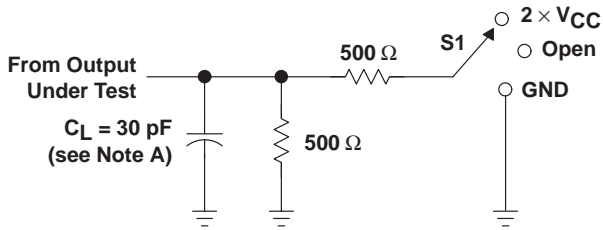


SN54ALVTH16244, SN74ALVTH16244
2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

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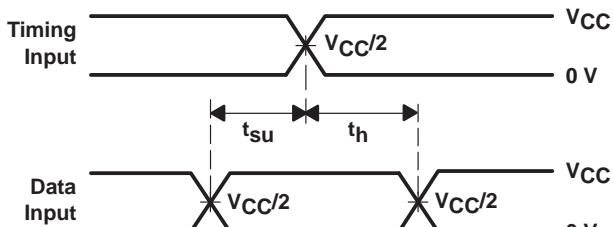
PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$

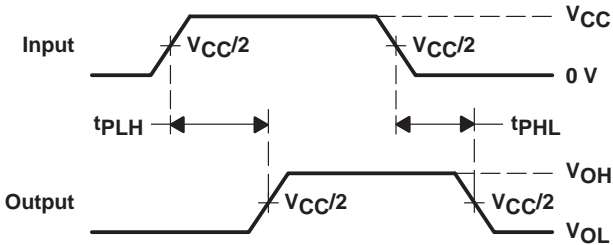


LOAD CIRCUIT

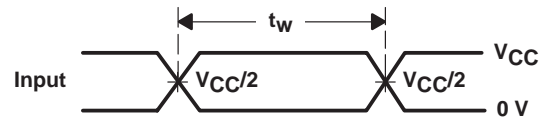
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 $\times V_{CC}$
t_{PHZ}/t_{PZH}	GND



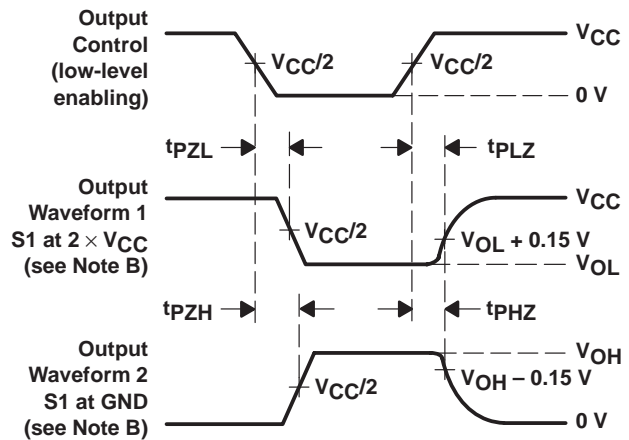
**VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES**



**VOLTAGE WAVEFORMS
PULSE DURATION**



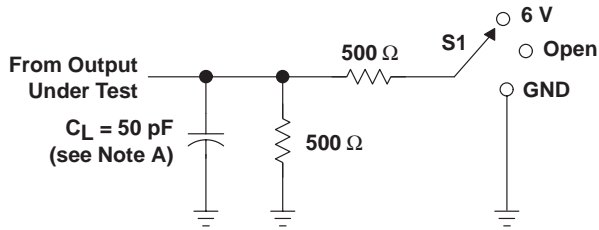
**VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES**

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR $\leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 2\text{ ns}$, $t_f \leq 2\text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

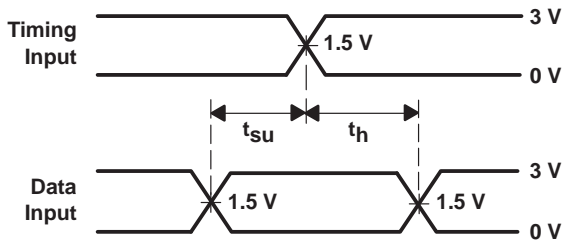
PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$

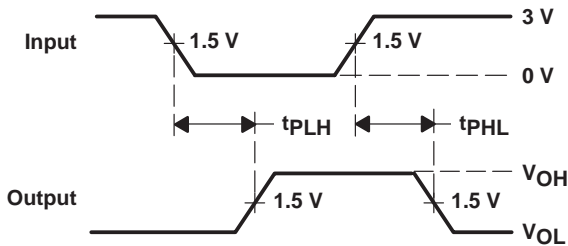


LOAD CIRCUIT

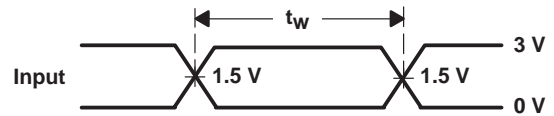
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



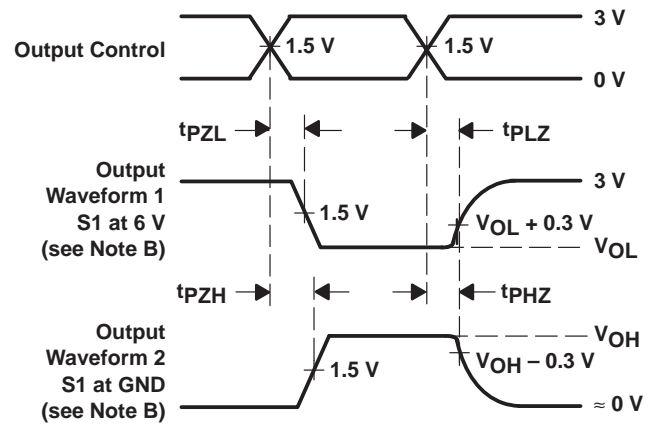
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.
D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
74ALVTH16244DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
74ALVTH16244DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
74ALVTH16244GRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
74ALVTH16244GRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
74ALVTH16244VRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
74ALVTH16244VRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
74ALVTH16244ZQLR	ACTIVE	BGA MICROSTAR JUNIOR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	
SN74ALVTH16244DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALVTH16244DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALVTH16244GR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALVTH16244VR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ALVTH16244ZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	330.0	16.4	4.8	7.3	1.5	8.0	16.0	Q1
SN74ALVTH16244DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
SN74ALVTH16244GR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74ALVTH16244VR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1

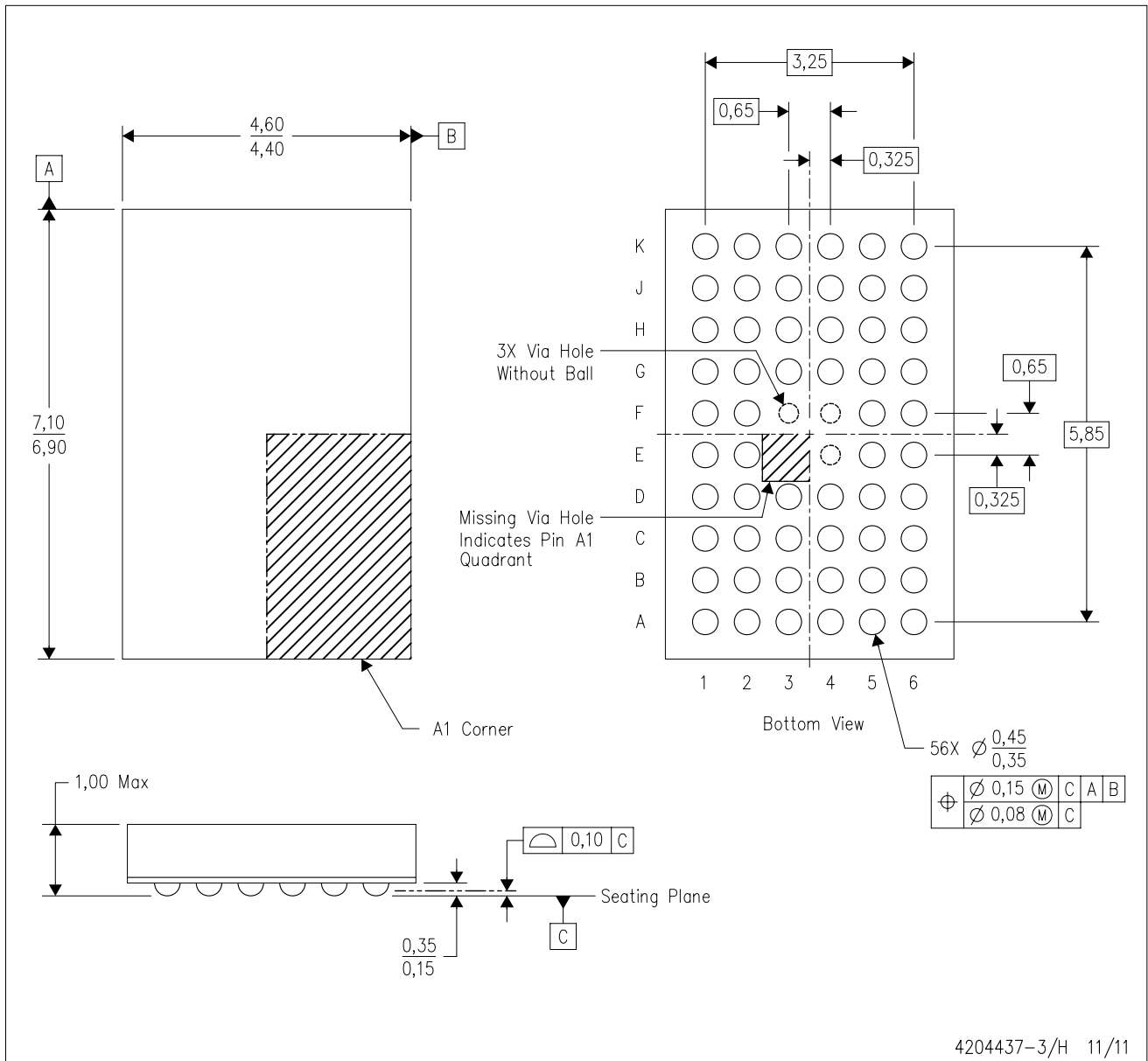
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ALVTH16244ZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	333.2	345.9	28.6
SN74ALVTH16244DLR	SSOP	DL	48	1000	367.0	367.0	55.0
SN74ALVTH16244GR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74ALVTH16244VR	TVSOP	DGV	48	2000	367.0	367.0	38.0

ZQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-285 variation BA-2.
 - D. This package is Pb-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN

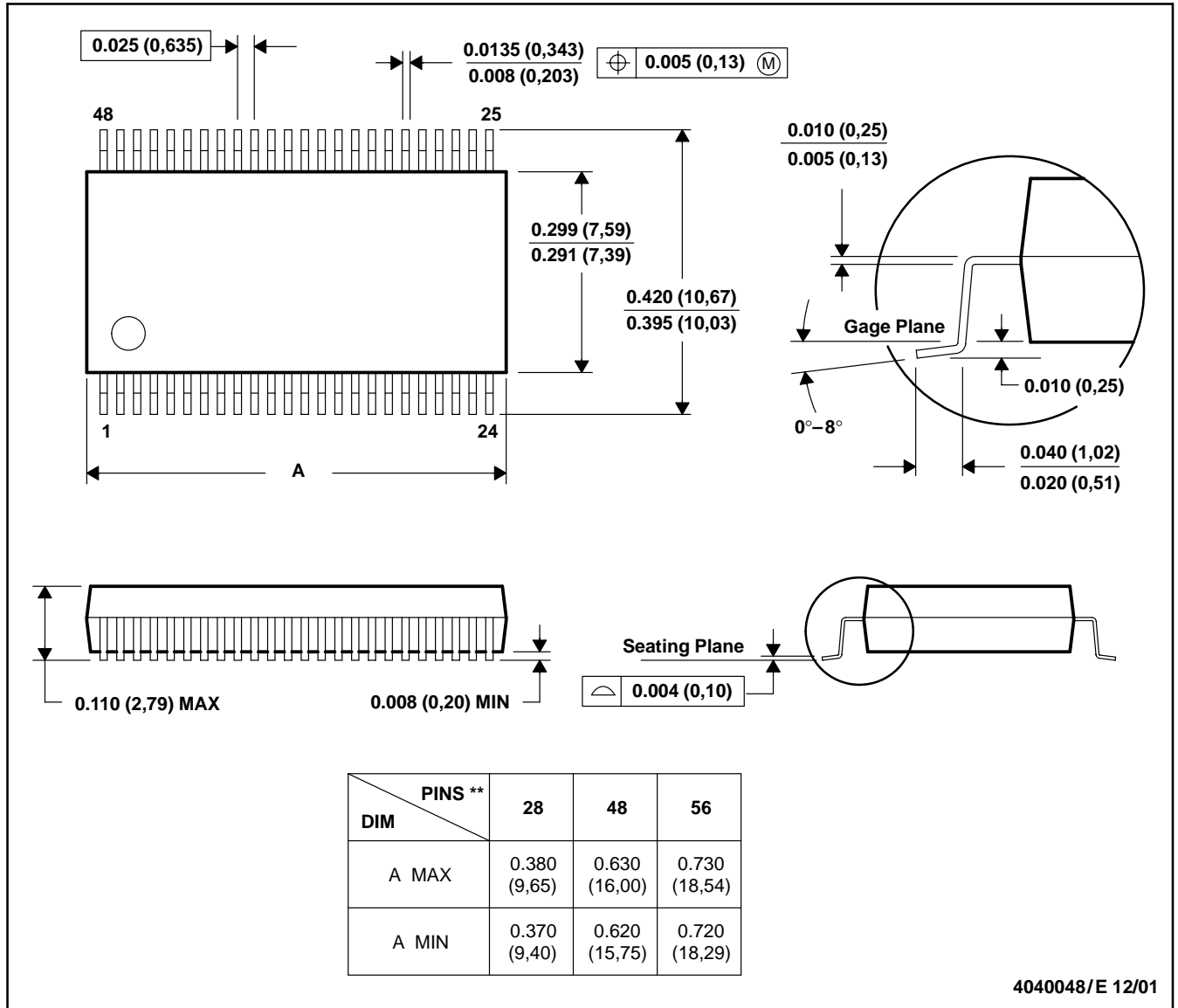


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

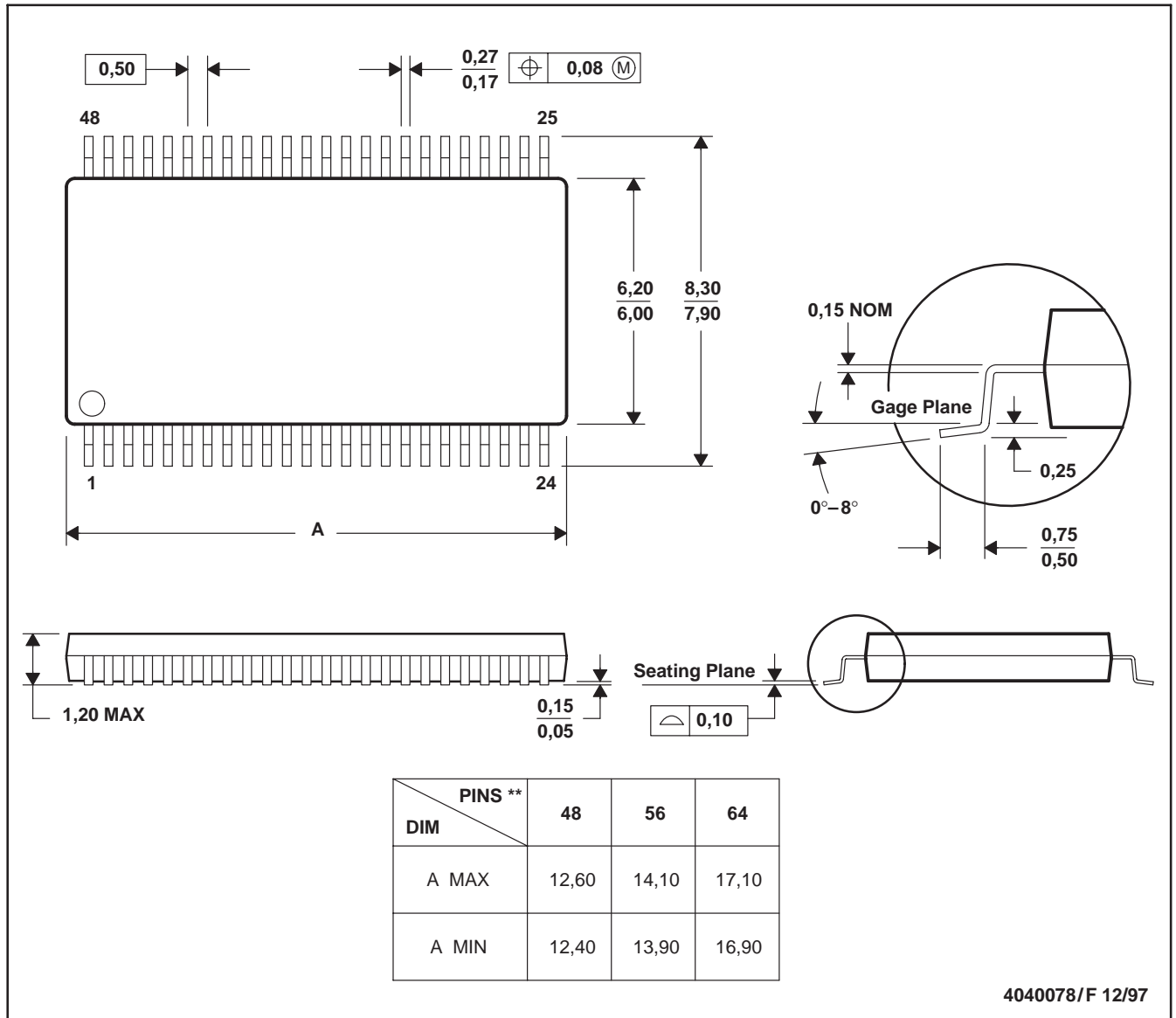


- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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